

PRODUCT DATA SHEET

SikaBond® T-85

Hybrid urethane adhesive, moisture vapor and sound reduction membrane

PRODUCT DESCRIPTION

SikaBond®-T85 is a one component, zero VOC, permanently elastic, super strong, very low permeability, moisture-cure, all-in-one hybrid polyurethane adhesive that offers moisture protection, crack bridging and sound reduction for full surface wood floor bonding.

USES

SikaBond®-T85 may be used for solid and engineered wood floors (strips, longstrips, planks, panels, boards), mosaic parquet, industrial parquet, wood paving (residential) as well as chip boards and plywood. Once cured, SikaBond®-T85 will generate a super strong bond to a variety of substrates for glue down installations and at the same time form a membrane which reduces moisture vapor transmission from the subfloor and sound reduction membrane.

CHARACTERISTICS / ADVANTAGES

- 150% Elongation
- Bonds up to 3/4" solid and engineered wood
- Cleans off prefinished floors before and after cure
- Controls MVER up to 15 lbs./85% RH
- Contains no water, solvent or isocyanates
- Low moisture vapor permeability
- Sound protection - meets local IIC and STC requirements
- Crack Bridging
- Very easy to spread
- Zero VOCs
- Low odor
- High elongation and permanently elastic - allows planks to expand and contract without damage to the adhesive

ENVIRONMENTAL INFORMATION

EED® V4.1	SCAQMD, Rule	BAAQMD, Reg. 8,
CDPH Standard	1168	Rule 51-226 (20
Method v1.2	(25 g/L limit)	g/L limit)
passes	passes	passes

APPROVALS / STANDARDS

- Independently tested to - STC 62 (ASTM E-90) when used as a sound control membrane at the specified coverage.
- Independently tested to IIC = 67 (ASTM E-492) when used as a sound control membrane at the specified coverage.

PRODUCT INFORMATION

Chemical Base	Hybrid Polymer
Packaging	4 gal. (15.14 L)
Color	Off-white
Shelf Life	12 months from date of production if stored in undamaged original sealed containers
Storage Conditions	Keep in dry conditions and protected from direct sunlight at temperatures between 50 °F and 77 °F (10–25 °C)
Density	1.64 kg/L Water Vapor Permeability is < 4 g/mmHg, 24h, m2 according to ASTM E-96 (< 4 Perms)
Texture	Easy to spread

TECHNICAL INFORMATION

Tensile Strength	150 psi (1.03 MPa)	(7 days at 74 °F (24 °C) and 50 % R.H.)
Shear Strength	2.0 N/mm ² , 1 mm adhesive thickness	(74 °F (24 °C) and 50 % R.H.)
Service Temperature	-40–150 °F (-40–65 °C)	
Elongation at break	150 %	(7 days at 74 °F (24 °C) and 50 % R.H.)

APPLICATION INFORMATION

Coverage

MOISTURE AND SOUND CONTROL			
Flooring Type		Trowel	Coverage
Solid or Engineered	Solid: Max Thickness: 3/4" Max Width: 8"	1/4" x 1/4" V-Notch 	30-35 sq.ft. per gal.
	Eng: Max Thickness: 3/4" Max Width: Unlimited	SCMB: 1/8" x 5/32" x 3/16" 	30-35 sq.ft. per gal.
For Moisture & Sound Control: 100% adhesive coverage to concrete and 100% adhesive transfer to back of board is required			
FOR USE AS ADHESIVE ONLY			
Flooring Type		Trowel	Coverage
Solid	Max Thickness: 3/4" Max Width: 8"	P5: 3/16" x 3/16" x 3/16" Flat V-notch 	45-50 sq.ft per gal.
Engineered	Thickness: 3/4" Max Width: Unlimited		
FOR USE WITH UNDERLAYMENT			
Flooring Type		Trowel	Coverage
Cork or rubber underlayment		1/8" x 1/8" Square notch* 	~80 sq.ft. per gal.

*Recommended trowel size for 3.2mm material

- Coverage must be monitored to ensure accuracy of application. Trowel angle may prevent proper coverage.
- Applicator is responsible for periodic inspection of the trowel to check for excessive wear. Worn trowels must be replaced immediately.
- In case of uneven substrates, it may be necessary to use a notched trowel

- with bigger notches (avert hollow sections).
- Coverage must be monitored to ensure accuracy of application. Trowel angle may prevent proper coverage.
- Trowel size is recommended to obtain proper coverage larger sizes are acceptable. Excessive amounts of adhesive may cause wood flooring to slide while placing check coverage during installation.
- P5 trowels should be used at 90° angle, SC+MB trowel or 1/4 in. (6.3 mm) x 1/4 in. (6.3 mm) V-notch at 45° angle to subfloor to get stated coverages.
- Substrate Quality: Structurally sound, clean, dry, homogeneous, even, free from grease, dust and loose particles, paint, laitance, and other poorly adhering particles must be removed.
- The P5 and SC+MB trowel are available from Sika.

Ambient Air Temperature	Room temperature between 50 °F (15 °C) and 90 °F (35 °C). For ambient temperatures standard construction guidelines should be followed. Follow all wood floor manufacturers' acclimation and room temperature requirements.	
Relative Air Humidity	Between 40 % and 70 % during installation is best for adhesive. See wood floor manufacturer for wood requirements.	
Substrate Temperature	During laying and until SikaBond®-T85 has fully cured, substrate temperature should be greater than 60 °F (15 °C) and in the case of radiant floor heating, less than 70 °F (20 °C). For substrate temperatures, standard construction guidelines should be followed.	
Substrate Moisture Content	<p>For use as an adhesive only: SikaBond® T-85 is not affected by moisture or vapor transmission. For protection of the wood, follow the wood floor manufacturer's requirements for subfloor moisture. If substrate is not acceptable, use SikaBond® T-85 at recommended coverage rate as All-in-One or Sika® MB. See Technical Data Sheet for proper instruction.</p> <p>For use as an adhesive and moisture membrane: Concrete moisture vapor emission rate (MVER) may not exceed 12 lbs. per 1,000 sq.ft. (5,44 kg per 92,9 m2) per 24 hours, anhydrous calcium chloride test (ASTM F1869). Do not install when the relative humidity (RH) of the concrete slab exceeds 85% (ASTM F2170).</p>	
Curing Rate	Floor may accept light foot traffic after: 8 hours Floor can be sanded after 18 hours.	
Skin Time / Laying Time	45 min	74 °F 50 % R.H.

BASIS OF PRODUCT DATA

Results may differ based upon statistical variations depending upon mixing methods and equipment, temperature, application methods, test methods, actual site conditions and curing conditions.

USES

- Wood size limitations can be found in coverage section
- P5 trowel or larger must be used with all solid woods and when applying over gypsum based sub floor (for use as an adhesive only)
- SC+MB or 1/4 in. (6.3 mm) x 1/4 in. (6.3 mm) trowel must be used for use as an adhesive and vapor retarder membrane. Follow the wood floor manufacturer's installation instructions.
- Periodically check coverage of adhesive during installation: 100 % substrate coverage and adhesive

transfer is required to protect against damages from subfloor moisture.

- Minimum age of concrete before application is 21–28 days, depending on curing and drying conditions.
- Room temperatures should be between 50 °F (10 °C) and 90 °F (32 °C) during installation unless otherwise specified limitations by wood flooring manufacturer.
- Do not use on wet, contaminated or friable substrates.
- When needed, Sika® recommends the use of Sika® Level patching and levelling compounds for best results.
- Gypsum based sub-floors are very susceptible to excess moisture and will be degraded if exposed to excess moisture from below or above.
- Solid wood and bamboo flooring cannot be used below grade due to their lack of dimensional stability.
- Do not use in areas subject to hydrostatic head or in areas subject to secondary source of moisture.
- On-or below-grade substrates must have appropriate vapor barrier (< 6 mil, 0.15 mm) properly installed

- below slab.
- Do not use over concrete with curing compounds, sealers or other surface treatments that could impact the adhesion.
- This adhesive will not prevent all possible moisture related or installation related issues such as improper acclimation of flooring, jobsite temperature and relative humidity, etc.
- This membrane reduces moisture vapor emissions that originate from below the membrane only.
- This membrane does NOT reduce issues originating from the ends, sides or top of flooring, i.e. puddles, water leaks, etc.
- Sub-floor should be level – do not use adhesive as a levelling agent.
- Cutback or other asphaltic based residue must be removed.
- Chemically treated woods (ammonia, wood stain, timber preservatives, etc.) and woods with high oil content must be tested for adhesion prior to application.
- Adhesive should be kept above 60 °F (15 °C) for best workability.
- Sufficient ambient moisture is necessary for proper curing.
- When bonding solid wood Sika recommends the use of straps to fully connect tongue and groove – especially when wood pieces are not perfectly straight – ensure starter rows are set and properly cured to handle tension from straps.
- Installations over radiant heat require that slab temperature be kept below 70 °F (21 °C) during installation and for 48 hours after installation – then raised slowly up to final desired temperature. Follow wood floor manufacturer’s temperature guidelines.
- Do not expose SikaBond® T-85 to alcohol.

ENVIRONMENTAL, HEALTH AND SAFETY

APPLICATION INSTRUCTIONS

SUBSTRATE QUALITY

Substrate must be clean and dry, homogeneous, even, free from grease, dust and loose particles. Paint, laitance and other poorly adhering particles must be removed by mechanical means.

SUBSTRATE PREPARATION

- SikaBond® T-85 can be used on properly prepared, structurally sound concrete, cementitious patch/underlayments, chipboards, ceramic tiles, plywood.
- Concrete substrate must have a concrete surface profile of CSP 1-3.
- For on-grade subfloors Sika® recommends the use of Sika® MB, Sika® MB Redline, and Sika® MB EZ Rapid for best protection against sub-floor moisture – moisture testing is required by the wood flooring manufacturer for best results with the wood flooring products.
- Below grade applications are generally not

recommended unless proper precautions are taken to protect the wood flooring from sub-floor and in-room humidity extremes.

- A 3,000 psi compressive strength is the minimum requirement needed for SikaBond wood floor installations, including glue-down wood floors, or glued/mechanically anchored subfloors. Sika products such as SikaLevel®-01 Primer Plus, Sika® MB, Sika® MB Redline, and Sika® MB EZ Rapid can be used on substrates as consolidators to satisfy the minimum psi compressive strength requirements.
- Preparation is a critical step in the installation process and will ensure a successful long term tenacious bond.
- All concrete, cement screed and gypsum based subfloors must be structurally sound, clean, dry, smooth; free of voids, projections, loose materials, oil, grease, sealers and other surface contaminants. Thoroughly clean with an industrial vacuum. Remove laitance or weak areas mechanically and thoroughly.
- For application over ceramic tiles it is necessary to grind tile surfaces and clean thoroughly with an industrial vacuum.
- For substrates with old well bonded non-water-soluble adhesive or adhesive residue use Sika® MB, Sika® MB Redline, or Sika® MB EZ Rapid – see appropriate product data sheet for installation instructions and proper details. If surface contains asphalt (cutback) adhesive, follow the Resilient Floor Covering Institute “Recommended Work Practices” for removal. When the asphalt (cutback) adhesive is sufficiently removed use the Sika® MB, Sika® MB Redline, or Sika® MB EZ Rapid to help promote adhesion to the subfloor or use a Sika® Level patch/level product in conjunction with the correct primer.
- SikaBond® T-85 will adhere to most common patching/levelling compounds. Due to differences in asphalt-based adhesive types and performance capabilities, applicators must verify that preparation of the surface is sufficient prior to using Sika® MB or Sika® Level patch/level compound. For unknown substrates, please contact Sika® Technical Services for best practices at 1-800-933-SIKA.

APPLICATION METHOD / TOOLS

Read and understand data sheet completely before beginning installation. Follow all industry standards, as well as hardwood and bamboo flooring manufacturer’s recommendations for floor flatness, acclimation, design, layout, application, etc. of wood flooring material. If jobsite conditions are outside of flooring manufacturer’s recommendations, take necessary corrective actions as recommended by the floor manufacturer to address these issues. Whether the moisture content of substrate exceeds or is within the manufacturer’s recommendations, to address current or possible future subfloor moisture, apply SikaBond® T-85 as directed. SikaBond® T-85 is applied to the properly prepared substrate directly from the pail and uniformly distributed by trowel as described on this Product Data Sheet. Press the wood floor elements firmly into the

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adhesive so that the wood floor underside is sufficiently wetted. The elements can then be joined together using a rubber hammer and an impact block and/ or rubber mallet. Many types of wood floors have to be tapped from the top. Leave gaps at room perimeters and at any floor wall partition to allow wood flooring to move naturally – follow recommended guidelines from wood floor manufacturer. Spacers should be used to ensure perimeter space is maintained. The wood flooring manufacturer’s laying instructions, acclimation requirements, room humidity/environmental control requirements as well as standard construction rules must be observed.

Plywood over concrete

Use a minimum 3/4” (18.3 mm) subfloor panel cut to smaller 2’ x 8’ or 4’ x 4’ sections. Kerf the back of the panels 1/2 the thickness of the material (3/8”) on a 12” x 12” grid. Lay sections in a staggered joint pattern in the adhesive, with 1/8” spacing between sheets, and 3/4” minimum expansion space at walls and all vertical obstructions. Flatness tolerances should be to within 3/16” in 6’ or 1/4” in 10’ for nail down over the wood subfloor. Do not use flooring fasteners longer than 3/4” to be certain not to puncture the moisture control membrane. Using a Sika P5 trowel, apply adhesive/membrane to substrate and then set plywood into the wet adhesive/membrane. For adhesion only, ensure at least 90% coverage and transfer. For moisture protection, ensure 100% coverage and transfer. Allow the adhesive/membrane to fully cure before nailing or using the SikaBond adhesive/ membrane to install flooring. Make sure that nails do not penetrate through the adhesive membrane.

Crack Preparation

All moving joints and moving cracks must be honored up through the floor preparation and floor covering installation, finishing with an appropriate Sika flexible sealing compound. Dormant hairline cracks can be covered with Sika MB or Sika MB Redline. Dormant joints and dormant cracks greater than a hairline that will not be honored must be pre-filled in strict accordance with the installation instructions provided by the Sika Technical Service Department.

Removal

All tools must be cleaned immediately after use with SikaBond® Remover or standard industry cleaning solvent. Any adhesive that is permitted to cure on the tool will need to be removed by mechanical means. SikaBond® Remover can be used to remove

uncured or cured adhesive and fingerprints from wood surface.

OTHER RESTRICTIONS

See Legal Disclaimer.

LEGAL DISCLAIMER

- KEEP CONTAINER TIGHTLY CLOSED
- KEEP OUT OF REACH OF CHILDREN
- NOT FOR INTERNAL CONSUMPTION
- FOR INDUSTRIAL USE ONLY
- FOR PROFESSIONAL USE ONLY

Prior to each use of any product of Sika Corporation, its subsidiaries or affiliates (“SIKA”), the user must always read and follow the warnings and instructions on the product’s most current product label, Product Data Sheet and Safety Data Sheet which are available at usa.sika.com or by calling SIKA’s Technical Service Department at 1-800-933-7452. Nothing contained in any SIKA literature or materials relieves the user of the obligation to read and follow the warnings and instructions for each SIKA product as set forth in the current product label, Product Data Sheet and Safety Data Sheet prior to use of the SIKA product.

SIKA warrants this product for one year from date of installation to be free from manufacturing defects and to meet the technical properties on the current Product Data Sheet if used as directed within the product’s shelf life. User determines suitability of product for intended use and assumes all risks. User’s and/or buyer’s sole remedy shall be limited to the purchase price or replacement of this product exclusive of any labor costs. **NO OTHER WARRANTIES EXPRESS OR IMPLIED SHALL APPLY INCLUDING ANY WARRANTY OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE. SIKA SHALL NOT BE LIABLE UNDER ANY LEGAL THEORY FOR SPECIAL OR CONSEQUENTIAL DAMAGES. SIKA SHALL NOT BE RESPONSIBLE FOR THE USE OF THIS PRODUCT IN A MANNER TO INFRINGE ON ANY PATENT OR ANY OTHER INTELLECTUAL PROPERTY RIGHTS HELD BY OTHERS.**

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Sika Corporation

201 Polito Avenue
Lyndhurst, NJ 07071
Phone: +1-800-933-7452
Fax: +1-201-933-6225
usa.sika.com



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